

Docket No.: **OKI.155D**

FORM PTO-1695 (Modified)  
 (Rev. 03-01)  
 OMB No. 0851-0027 (exp. 5/31/2002)  
 P08A/REV03

RECORDATION FORM COVER SHEET

U.S. DEPARTMENT OF COMMERCE  
 Patent and Trademark Office

**PATENTS ONLY**

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):  
OHSUMI, Takashi  
KATO, Yuzo

Additional names(s) of conveying party(ies)  Yes  No

2. Name and address of receiving party(ies):

Name: OKI ELECTRIC INDUSTRY CO., LTD.

Address: 7-12, Toranomom 1-chome, Minato-ku

3. Nature of conveyance:

Assignment  Merger

Security Agreement  Change of Name

Other \_\_\_\_\_

Execution Date: June 7 and 9, 2000

City: Tokyo State/Prov.: \_\_\_\_\_

Country: Japan ZIP: \_\_\_\_\_

Additional name(s) & address(es)  Yes  No

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is: \_\_\_\_\_

Patent Application No.	Filing date	B. Patent No.(s)
<u>09/916,320</u>	<u>July 30, 2001</u>	

Additional numbers  Yes  No

6. Total number of applications and patents involved: **1**

7. Total fee (37 CFR 3.41):.....\$ 40.00

Enclosed - Any excess or insufficiency should be credited or debited to deposit account

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5. Name and address of party to whom correspondence concerning document should be mailed:

Name: William S. Franco, Esquire

Registration No. 38,456

Address: VOLENTINE FRANCO S, P.L.L.C.

12200 Sunrise Valley Drive

Suite 150

City: Reston State/Prov.: VA

Country: USA ZIP: 20191

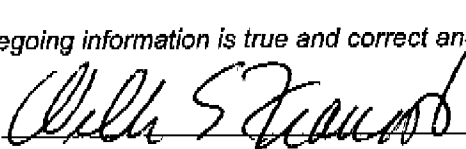
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9. Statement and signature.  
*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

William S. Francos  May 7, 2003

Name of Person Signing Signature Date

**3**

Total number of pages including cover sheet, attachments, and

**PATENT**

F 233 US

J O N E S  
V O L E N T I N E  
L.L.P. (4/99)

## ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned

Insert Name(s)  
of Inventor(s)

OHSUMI, Takashi

KATO, Yuzo

and

Insert Name(s)  
of Assignee(s)

the undersigned hereby sell(s) and assign(s) to

OKI ELECTRIC INDUSTRY CO., LTD.

Address

of 7-12, Toranomon 1-chome, Minato-ku, Tokyo, Japan

(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

Title of  
Invention

SEMICONDUCTOR WAFER AND METHOD FOR MANUFACTURING

SEMICONDUCTOR DEVICES

Date of Signing  
of Application

for which an application for patent in the United States of America has been executed by the undersigned

on June 7, 2000 and June 9, 2000

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) to Raymond C. Jones, Reg. No. 34,631 and Adam C. Volentine, Reg. No. 33,289, members of the firm of JONES VOLENTINE, L.L.P. the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date Jun. 9, 2000, Name of Inventor Takashi Ohsumi  
 Takashi OHSUMI

Date Jun, 7, 2000, Name of Inventor Y. Kato  
 Yuzo KATO

Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_

Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_

Date \_\_\_\_\_, Name of Inventor \_\_\_\_\_

(Note regarding Witnessing and/or Acknowledgment: Acknowledgment before a United States Consul is preferred but not required. If not acknowledged, then it is recommended that the execution by the Inventor(s) be witnessed by at least two witnesses who sign here. However, the current practice of the U.S. Patent and Trademark Office is to record an Assignment even if it has not been acknowledged and/or witnessed.)

Witness Shinji Ohuchi Shinji Ohuchi (for Ohsumi)

Witness Kiyoshi Hasegawa Kiyoshi Hasegawa (for Kato)

### ACKNOWLEDGMENT

\_\_\_\_\_ }  
 \_\_\_\_\_ } ss

This \_\_\_\_\_ day of \_\_\_\_\_, 19\_\_\_\_, before me personally came the above-named \_\_\_\_\_

to me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

\_\_\_\_\_  
Official Signature

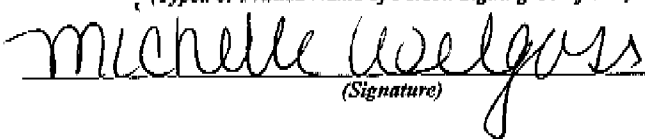
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\_\_\_\_\_  
Official Title

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Applicant Reference No.: F-2335-US-ED Atty Docket No.: OKI.155

Serial No.: \_\_\_\_\_ Filing Date: MARCH 9, 2000

CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)			Docket No.
Applicant(s):			OKI.155D
Serial No. 09/916,320	Filing Date July 30, 2001	Examiner Christian D. Wilson	Group Art Unit 2824
Invention: SEMICONDUCTOR WAFER AND METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICES			
I hereby certify that this _____ <u>Assignment</u> _____ (Identify type of correspondence) is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. <u>(703) 306-5995</u> ) on _____ <u>May 7, 2003</u> _____ (Date)			
Michelle Welgoss (Typed or Printed Name of Person Signing Certificate)  (Signature)			
Note: Each paper must have its own certificate of mailing.			

PATENT

P18/REV01

RECORDED: 05/07/2003

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